

BR1N4007WQ

Rev.A Sep.-2024

/ Descriptions

SOD-123FL

Surface Mount General Purpose Silicon Rectifiers Reverse Voltage 1000V Forward Current 1A
SOD-123FL thin package.

/ Features

RoHS 2011/65/EU

Glass Passivated Chip Junction Ideal for automated placement Lead free in comply with EU RoHS 2011/65/EU directives For surface mounted applications, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

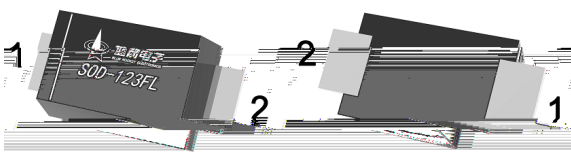
/ Applications

General purpose, Meet the stringent requirements of automotive applications.

/ Equivalent Circuit

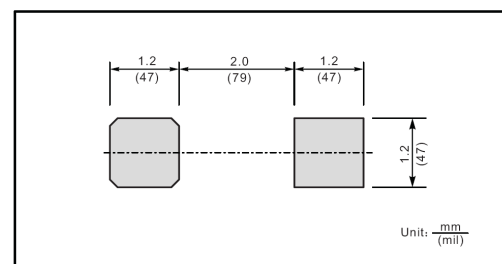


/ Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



/ Marking

See Marking Instructions.

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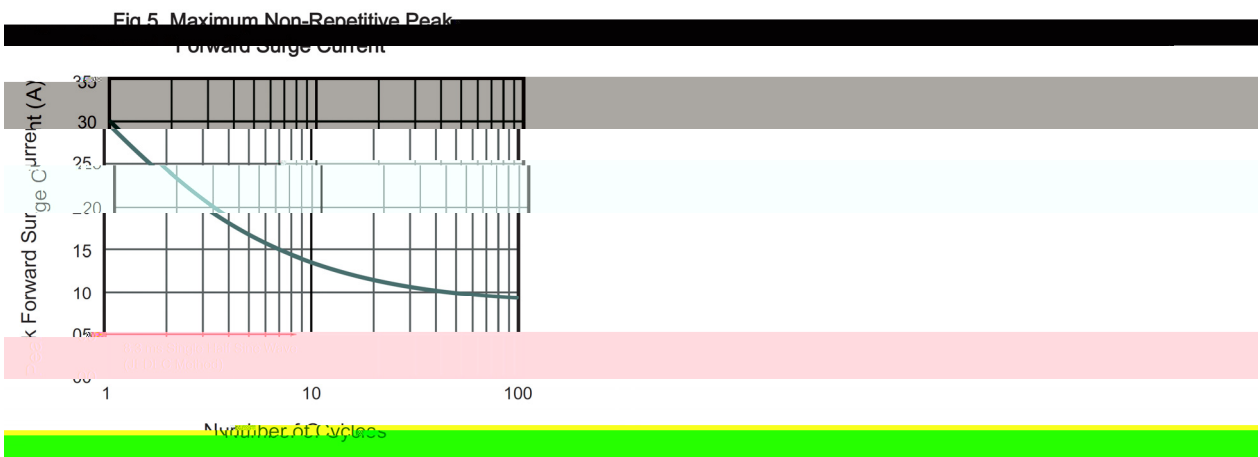
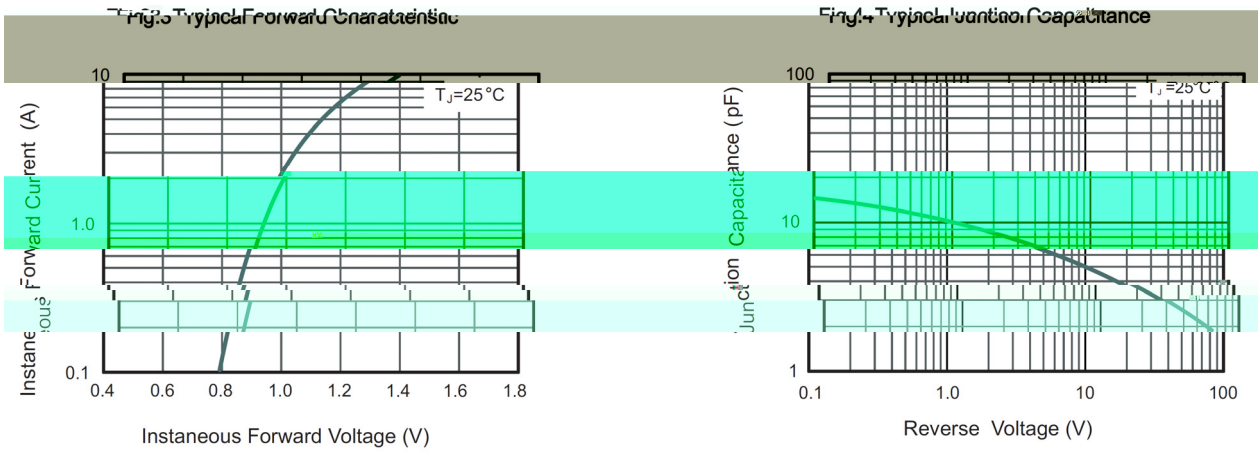
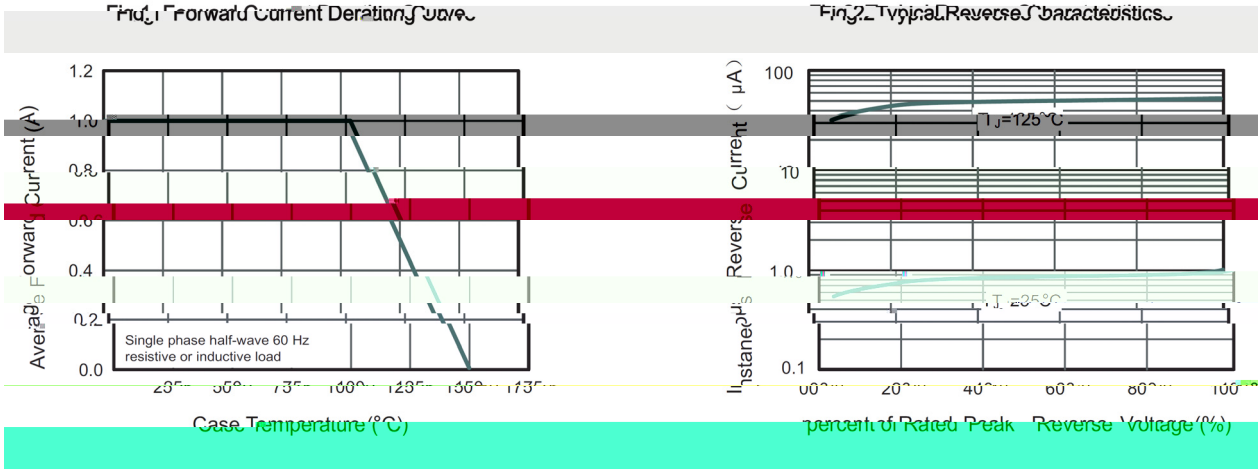
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DATA SHEET

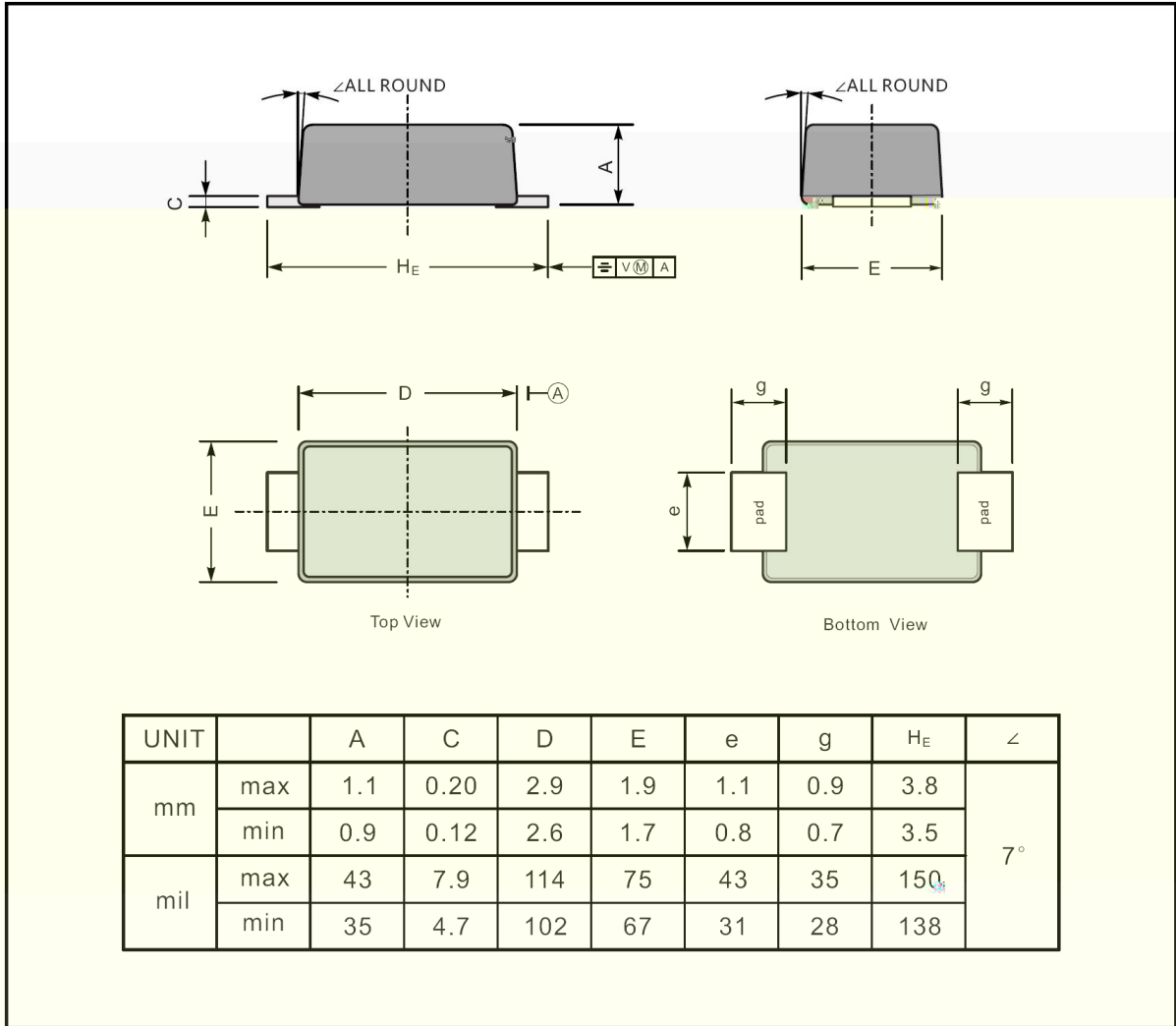
Parameter	Symbol	Rating	Unit
		BR1N4007WQ	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS Voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Maximum Average Forward Rectified Current @ Fig.1	$I_{F AV}$	1	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	30	A
Peak Forward Surge Current 1.0 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	60	A

/ Electrical Characteristic Curve

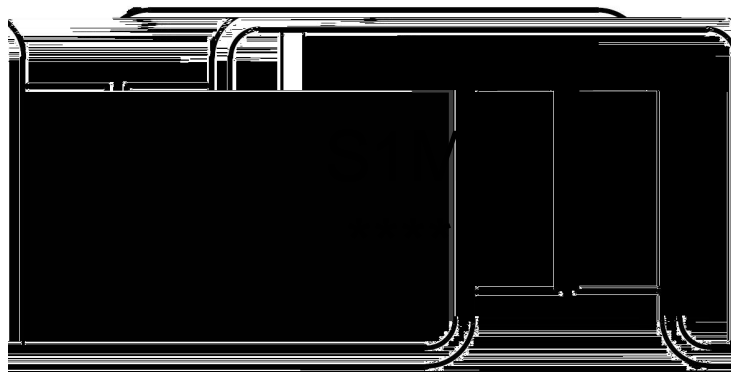


/ Package Dimensions

SOD-123FL



/ Marking Instructions

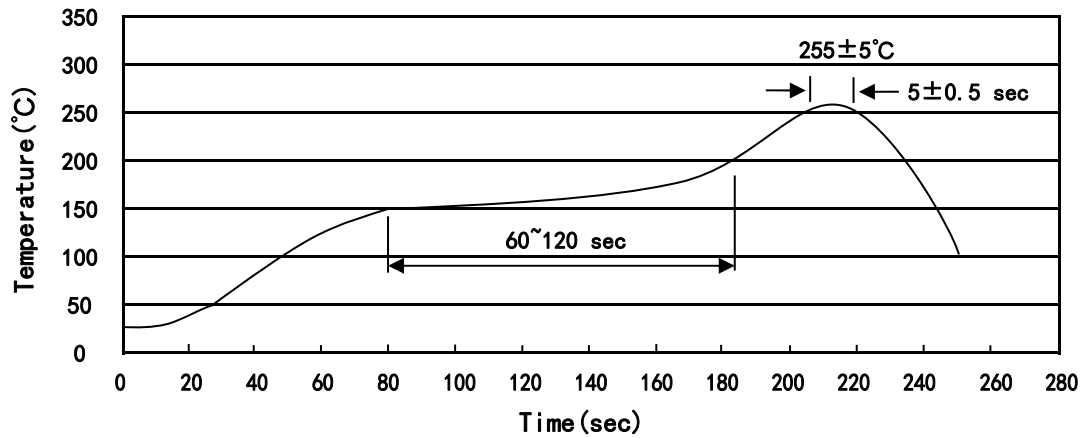


Note:

Product Type Code

Lot No. Code, code change with Lot No

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1 150 200 60 120sec; 1.Preheating:150~200 , Time:60~120sec.
- 2 255 5 5 0.5sec; 2.Peak Temp.:255 5 , Duration:5 0.5sec.
- 3 2 10 /sec. 3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
SOD-123FL	3,000	8	24,000	6	144,000	7 x8	185x180x105	390x385x205

/ Notices